Silicon N-Channel/P-Channel Power MOS FET Array

HITAÇHI

Application

High speed power switching

Features

· Low on-resistance

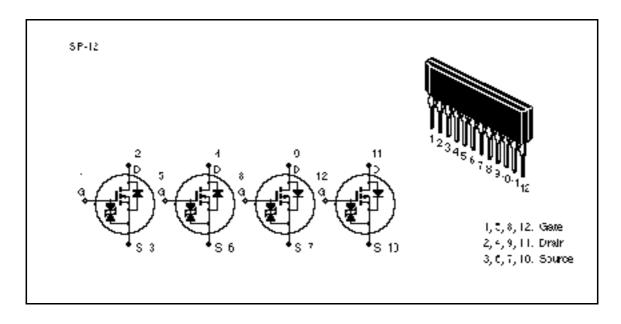
N Channel: $R_{DS(on)}$ 0.17 , $V_{GS}=10$ V, $I_D=4$ A P Channel: $R_{DS(on)}$ 0.2 , $V_{GS}=-10$ V, $I_D=-4$ A

· High speed switching

• High density mounting

· Suitable for H-brided motor driver

Outline





Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

| | | Ratings | | | |
|---|--------------------------|---------|------|------|--|
| Item | Symbol | | Pch | Unit | |
| Drain to source voltage | V _{DSS} | 60 | -60 | V | |
| Gate to source voltage | V _{GSS} | ±20 | ±20 | V | |
| Drain current | I _D | 8 | -8 | А | |
| Drain peak current | l _{D(pulse)} *1 | 32 | -32 | А | |
| Body to drain diode reverse drain current | I _{DR} | 8 | -8 | A | |
| Channel dissipation | Pch (Tc = 25°C)*2 | 28 | | W | |
| | Pch*2 | 4.0 | | W | |
| Channel temperature | Tch | 150 | | °C | |
| Storage temperature | Tstg | –55 to | +150 | °C | |

Notes: 1. PW 10 µs, duty cycle 1%

2. 4 Device Operation

Electrical Characteristics ($Ta = 25^{\circ}C$)

N channel

| Item | Symbol | Min | Тур | Max | Unit | Test conditions |
|---|---------------------|-----|------|------|------|--|
| Drain to source breakdown voltage | $V_{(BR)DSS}$ | 60 | _ | _ | V | $I_D = 10 \text{ mA}, V_{GS} = 0$ |
| Gate to source breakdown voltage | $V_{(BR)GSS}$ | ±20 | _ | _ | V | $I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$ |
| Gate to source leak current | I _{GSS} | _ | _ | ±10 | μΑ | $V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$ |
| Zero gate voltage drain current | I _{DSS} | _ | _ | -250 | μΑ | $V_{DS} = 50 \text{ V}, V_{GS} = 0$ |
| Gate to source cutoff voltage | $V_{GS(off)}$ | 1.0 | _ | 2.0 | V | $I_{D} = 1 \text{ mA}, V_{DS} = 10 \text{ V}$ |
| Static drain to source on state | $R_{\text{DS(on)}}$ | _ | 0.13 | 0.17 | | $I_D = 4 \text{ A}, V_{GS} = 10 \text{ V}^{*1}$ |
| resistance | | _ | 0.18 | 0.24 | | $I_D = 4 \text{ A}, V_{GS} = 4 \text{ V}^{*1}$ |
| Forward transfer admittance | y _{fs} | 3.5 | 5.5 | _ | S | $I_D = 4 \text{ A}$ $V_{DS} = 10 \text{ V}^{*1}$ |
| Input capacitance | Ciss | _ | 400 | _ | pF | V _{DS} = 10 V |
| Output capacitance | Coss | _ | 220 | _ | pF | $V_{GS} = 0$ |
| Reverse transfer capacitance | Crss | _ | 60 | _ | pF | f = 1 MHz |
| Turn-on delay time | t _{d(on)} | _ | 5 | _ | ns | I _D = 4 A |
| Rise time | t _r | _ | 45 | _ | ns | $V_{GS} = 10 \text{ V}$ |
| Turn-off delay time | t _{d(off)} | _ | 150 | _ | ns | $R_{L} = 7.5$ |
| Fall time | t _f | _ | 85 | _ | ns | _ |
| Body to drain diode forward voltage | V_{DF} | _ | 1.2 | _ | V | $I_F = 8 \text{ A}, V_{GS} = 0$ |
| Body to drain diode reverse recovery time | t _{rr} | | 120 | | ns | $I_F = 8 \text{ A}, V_{GS} = 0,$ diF/dt = 50 A/µs |

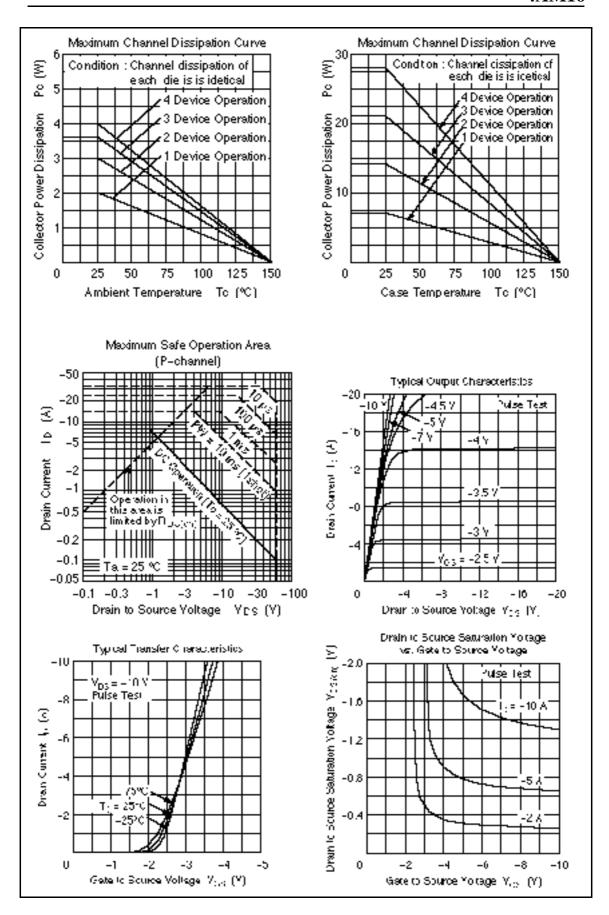
Note: 1. Pulse Test

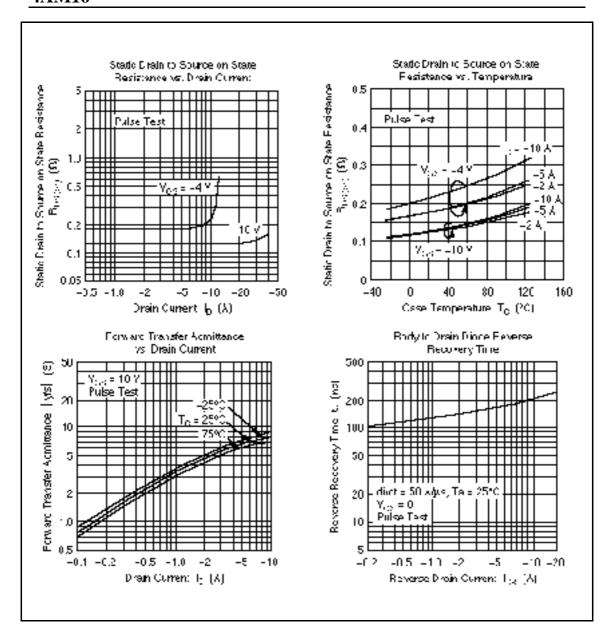
Electrical Characteristics ($Ta = 25^{\circ}C$)

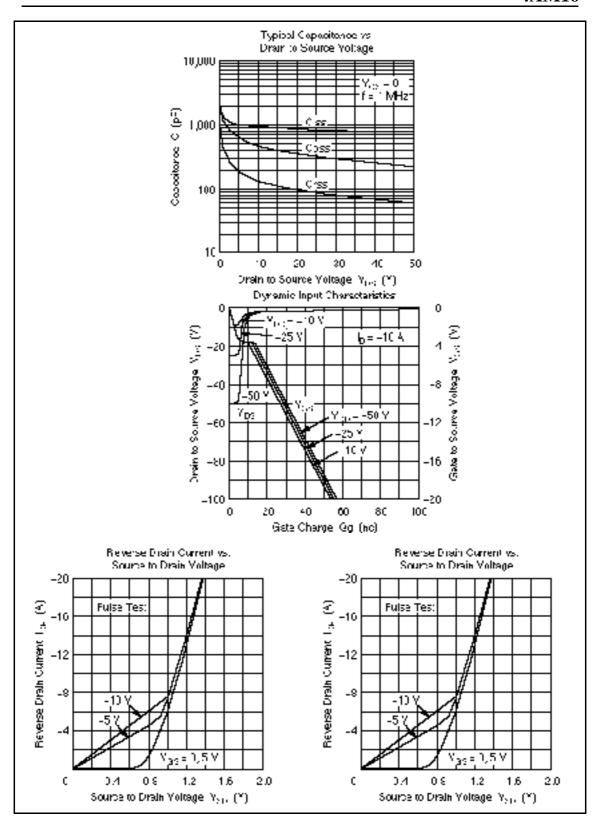
P channel

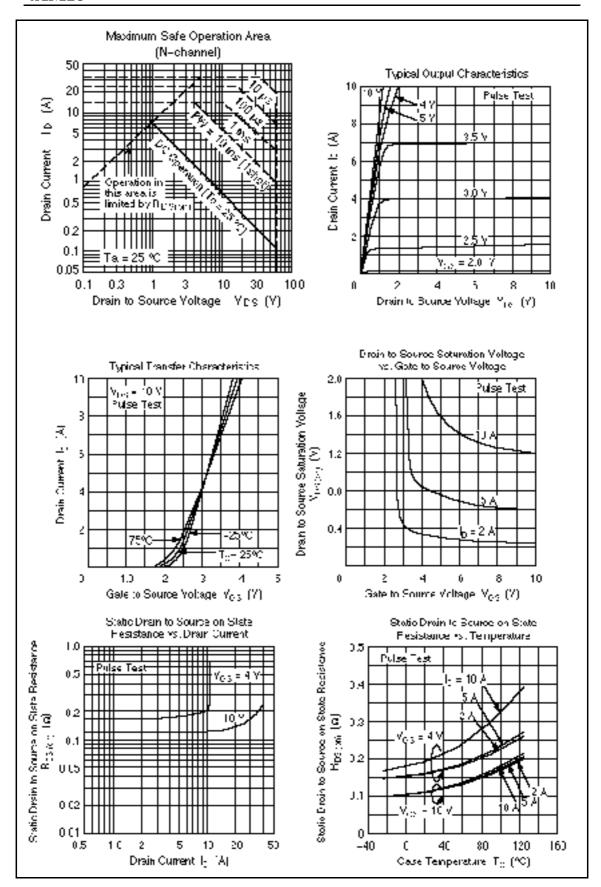
| | 1 Onamici | | | | | |
|---|---------------------|------|------|------|------|---|
| Item | Symbol | Min | Тур | Max | Unit | Test conditions |
| Drain to source breakdown voltage | $V_{(BR)DSS}$ | -60 | _ | _ | V | $I_D = -10 \text{ mA}, V_{GS} = 0$ |
| Gate to source breakdown voltage | $V_{(BR)GSS}$ | ±20 | _ | _ | V | $I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$ |
| Gate to source leak current | I _{GSS} | _ | _ | ±10 | μΑ | $V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$ |
| Zero gate voltage drain current | I _{DSS} | _ | _ | -250 | μΑ | $V_{DS} = -50 \text{ V}, V_{GS} = 0$ |
| Gate to source cutoff voltage | $V_{GS(off)}$ | -1.0 | _ | -2.0 | V | $I_D = -1 \text{ mA}, V_{DS} = -10 \text{ V}$ |
| Static drain to source on state | $R_{\text{DS(on)}}$ | _ | 0.15 | 0.20 | | $I_D = -4 \text{ A}, V_{GS} = -10 \text{ V}^{*1}$ |
| resistance | | _ | 0.20 | 0.27 | | $I_D = -4 \text{ A}, V_{GS} = -4 \text{ V}^{*1}$ |
| Forward transfer admittance | y _{fs} | 3.5 | 6.0 | _ | S | $I_D = -4 A$ $V_{DS} = -10 V^{*1}$ |
| Input capacitance | Ciss | _ | 900 | _ | pF | V _{DS} = -10 V |
| Output capacitance | Coss | _ | 460 | _ | pF | $V_{GS} = 0$ |
| Reverse transfer capacitance | Crss | _ | 130 | _ | pF | f = 1 MHz |
| Turn-on delay time | t _{d(on)} | _ | 8 | _ | ns | $I_D = -4 A$ |
| Rise time | t _r | _ | 50 | _ | ns | $V_{GS} = -10 \text{ V}$ |
| Turn-off delay time | t _{d(off)} | _ | 180 | _ | ns | $R_{L} = 7.5$ |
| Fall time | t _f | _ | 95 | _ | ns | _ |
| Body to drain diode forward voltage | V_{DF} | _ | -1.2 | _ | V | $I_F = -8 \text{ A}, V_{GS} = 0$ |
| Body to drain diode reverse recovery time | t _{rr} | _ | 185 | _ | ns | $I_F = -8 \text{ A}, V_{GS} = 0,$ diF/dt = 50 A/ μ s |
| | | | | | | |

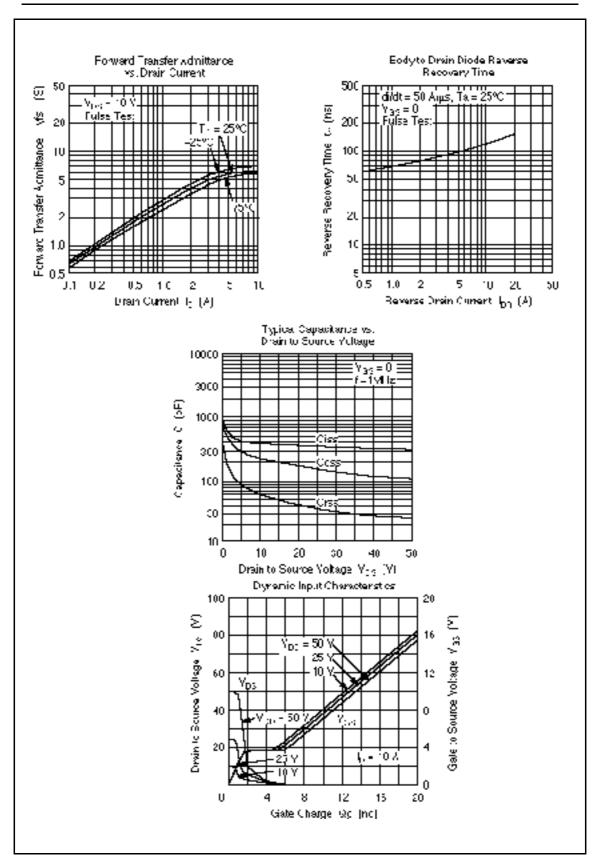
Note: 1. Pulse Test

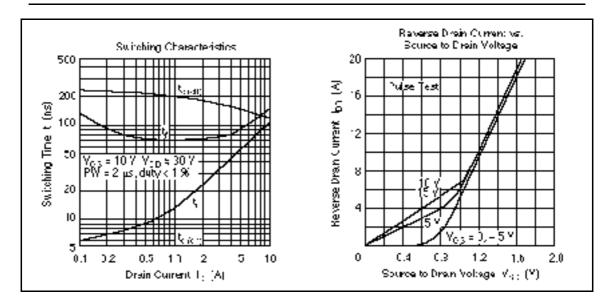












When using this document, keep the following in mind:

- 1. This document may, wholly or partially, be subject to change without notice.
- 2. All rights are reserved: No one is permitted to reproduce or duplicate, in any form, the whole or part of this document without Hitachi's permission.
- 3. Hitachi will not be held responsible for any damage to the user that may result from accidents or any other reasons during operation of the user's unit according to this document.
- 4. Circuitry and other examples described herein are meant merely to indicate the characteristics and performance of Hitachi's semiconductor products. Hitachi assumes no responsibility for any intellectual property claims or other problems that may result from applications based on the examples described herein.
- 5. No license is granted by implication or otherwise under any patents or other rights of any third party or Hitachi, Ltd.
- 6. MEDICAL APPLICATIONS: Hitachi's products are not authorized for use in MEDICAL APPLICATIONS without the written consent of the appropriate officer of Hitachi's sales company. Such use includes, but is not limited to, use in life support systems. Buyers of Hitachi's products are requested to notify the relevant Hitachi sales offices when planning to use the products in MEDICAL APPLICATIONS.

HITACHI

Hitachi, Ltd.
Semiconductor & IC Div.
Nepon Bidg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokiyo 100, Japan
Tet Tokyo (03, 3270-2414
Fex: (03, 3270-5409

For further in formellon write to:

Historii Americe, Lbd. Semiconductor & IC Dw. 2000 Sierre Point Perlaway Briebene, CA. 94005-4835 U.S.A. Tet 445-580-8800

Fex: 415-583-4207

Hitechi Burope GmbH
Bedronic Componente Group
Cartinertel Burope
Darrecher Streße 3
D-85622 Feldkirchen
München
Tet 089-9 94 80-0
Fex: 089-9 29 30 00

Hitschi Burope Ltd.
Bedronic Components Div.
Northern Burope Headquarters
Whitsbrook Park
Lower Cook hem Road
Meidenhead
Berkshire SL68YA
Urited Kingdom
Tet 0628-888000
Fex: 0628-778322

Hitachi Asia Pta, Ltd 45 Collyer Quay \$20-00 Hitachi Tower Snappore 0404 Tet 535-2400 Fex 535-4533

Hitachi Asia (Hong Kong) Ltd. Unit 705, North Towar, World Finance Cantra, Harbour City, Carton Road Taim She Taul, Kowloon Hong Kong Tet 27350218 Fax: 27306074